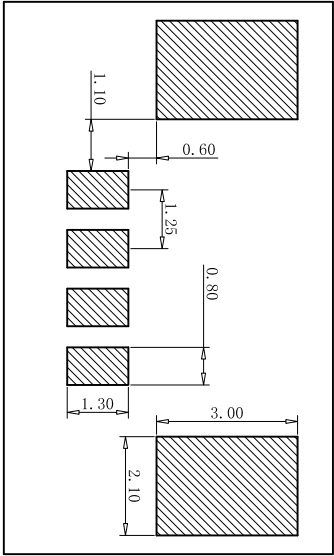
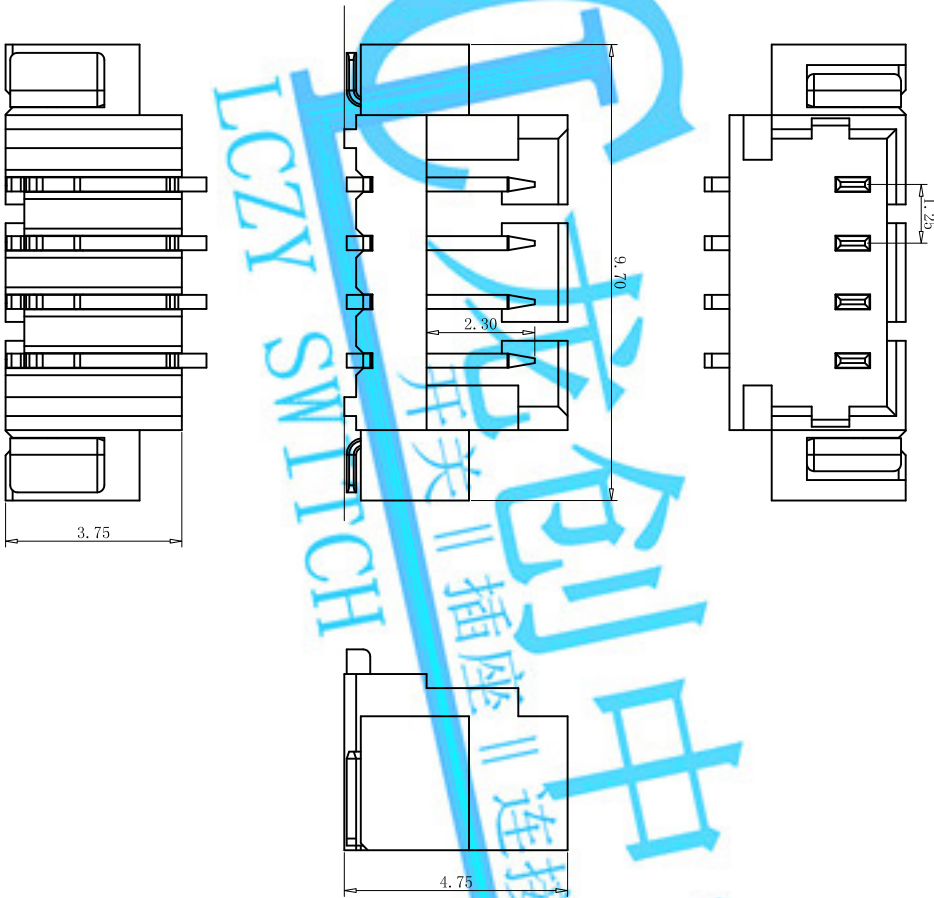


REV.	DESCRIPTION	APPD	DATE

NOTES:

1. MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL94V_0
CONTACT: COPPER ALLOYS.
COVER: COPPER ALLOYS OR STEEL.
2. PLATING:
UNDERPLATE: NICKEL.
3. MULTIMEDIA CARD COMPATIBLE



PART NO: WAF04-T1T1-2020-A	MATERIAL:	LONGCHUANG ZHONGYE (HK)CO.,LIMITED	
LOT NO:	FINISH:		
UNIT: MM	SIZE: A4		
TOLERANCES: GENERAL: X, Y=±0.35 X, XY=±0.25 X, XXX=±0.15		DR: 刘静	TITLE: WAFER 1.25 立贴
ANGLE: X, Y=±3.0° X, XY=±2.0°		CHK: 刘静	DWG NO: FP-090012
APP: 刘静		SCALE: 1:1	REV: A
		SHEET: 1 OF 1	